

CLAIMS

What is claimed is:

- 1 1. A method for forming a package for an electrical device, said method
2 comprising the steps of:
3 attaching a removable material to a surface of a conductive material;
4 forming isolated conductive features within said conductive material;
5 attaching encapsulant to said isolated conductive features and said removable
6 material; and
7 removing said removable material from said conductive features and said encapsulant.
- 1 2. The method for forming a package for the electronic device of claim 1,
2 wherein said forming step includes patterning a surface of said conductive material with a
3 material resistant to an etchant and etching said conductive material with said etchant.
- 1 3. The method for forming a package for the electronic device of claim 1,
2 further comprising the step of forming a die attach pad within said conductive material.
- 1 4. The method for forming a package for the electronic device of claim 1, further
2 comprising the step of coupling the device to said die attach pad.
- 1 5. The method for forming a package for an electronic device of claim 1, further
2 comprising the step of electrically coupling an input/output portion of the device to said
3 isolated conductive feature.
- 1 6. The method for forming a package for the electronic device of claim 1, further
2 comprising the step of singulating individual packaged devices.
- 1 7. The method of claim 1, wherein the removable material is water soluble
2 adhesive.
- 1 8. The method of claim 7, wherein the removable material is removed with
2 deionized water.

1 9. A method of forming a device package, said method comprising the steps of:
2 applying removable material to a leadframe;
3 attaching a device to said leadframe; and
4 attaching encapsulant to a portion of said device and a portion of said leadframe.

1 10. The method of forming a device package according to claim 9, further
2 comprising the step of exposing said leadframe to an etchant to form undercut regions
3 configured to assist attachment of said encapsulant to said leadframe.

1 11. The method of forming a device package according to claim 9, further
2 comprising the step of electrically coupling a portion of said device to said leadframe.

1 12. The method of forming a device package according to claim 9, further
2 comprising the step of forming isolated conductive features by sawing through a portion of
3 said leadframe.

1 13. The method of forming a device package according to claim 9, further
2 comprising the step of removing said removable material from said leadframe and said
3 encapsulant.

1 14. The method of claim 9, wherein the removable material is water soluble
2 adhesive.

1 15. The method of claim 14, wherein the removable material is removed with
2 deionized water.